

*Cmt C2*  
24. The optoelectronic device of claim 8, wherein multiple optical devices are arranged for optical communication through multiple respective spacer substrate apertures.

*C3*  
26. The optoelectronic device of claim 13, wherein multiple optical lenses are cooperatively arranged in optical alignment with multiple respective optical devices.

27. The optoelectronic device of claim 13, wherein multiple optical devices are arranged for optical communication through multiple respective spacer substrate apertures.

Please add the following new claims.

*C4*  
28. The optoelectronic device of claim 3, wherein each solder bump is in direct contact with respective metallization patterns of the optical device system and the optical lens system.

29. The optoelectronic device of claim 11, wherein each solder bump is in direct contact with respective metallization patterns of the optical device system and the optical lens system.

30. The optoelectronic device of claim 13, wherein the device substrate is a semiconductor substrate.

#### COMMENTS

##### I. Status of claims

Claims 3-27 were pending. Claims 13, 23, 24, 26, and 27 have been amended. Claims 28-30 have been added.